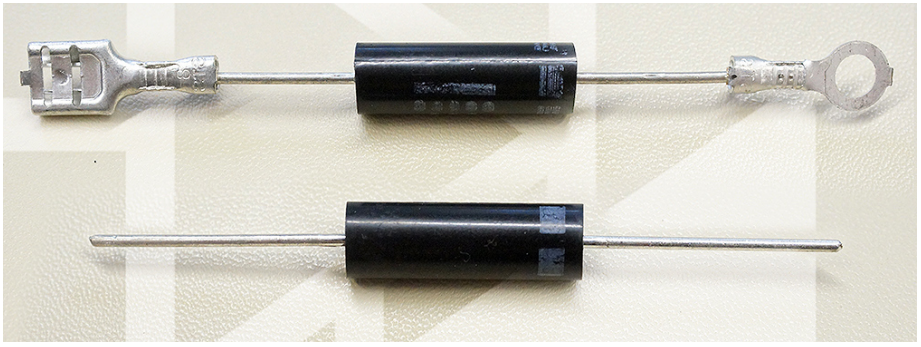
AMERICAN MICROSEMICONDUCTOR

AMS-01-15

Technical Specifications

FEATURES

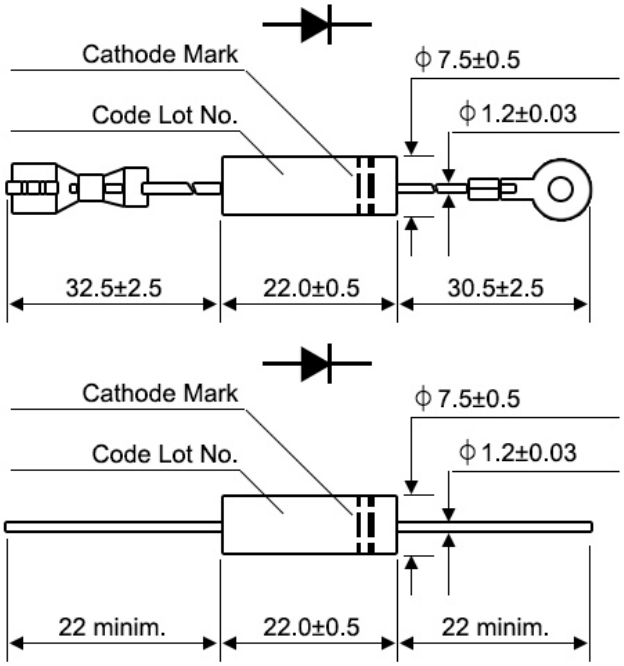
- High Overload Surge Capacity
- Durable Epoxy Resin Package



To order with quick disconnect terminals, use the ***partnum*-TERM**

ABSOLUTE MAXIMUM RATINGS

V_{RRM}	Repeating Peak Reverse Voltage (kV):	15
T_{JMAX}	Max. junction temp.(°C):	120
T_{STG}	Storage temp.(°C):	-40 to +120
I_O	Avg. Forward Current (mA):	350
I_{FSM}	Forward Surge Current (A):	30



ELECTRICAL CHARACTERISTICS

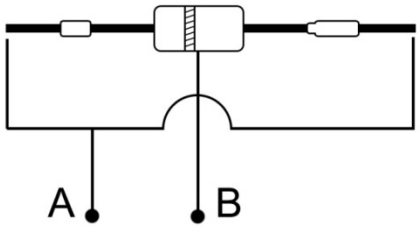
I_{R1} Normal temp. Reverse Current (μA) @ $V_R=V_{RRM}$:	2.0 max
I_{R2} High temp. Reverse Current (μA) @ $V_R=V_{RRM}$, T_{amb}=100°C:	50 max
V_F Forward Voltage Drop (V) @ I_F=350mA:	10.5

TEST CONDITIONS

High temp. Reverse Voltage @ 1000 hrs.:	$V_{RM}=V_{RRM}$, f=50Hz, T_{AMB}=100°C Half sine voltage with f=50Hz applied, T_{AMB}=100°C
High temp. storage @ 1000 Hrs.:	T_{AMB}=130±2°C
Soldering Resistance Heat Test:	Solder trough temp.: 350±10°C, Dip Time: 3.5s ± 0.5s
High pressure smoke test @ 10 hrs.:	120°C, 2 x 10^5pa
Insulation Resistance Test (1000MΩ):	Between the center of the body and terminal *(See Fig. 1)*
Insulation Strength Test @ 10KV:	1 min. between center of the body and terminal. *(Fig.1)*
Lead bend test:	Force 10 N to the lead, bent it to pos. and neg. 90°
Lead pull test:	Force 70 N of axial to the lead for 1 min.

Insulation resistance test condition: Measure between A and B by using a DC 500V Insulation resistance tester

Insulation strength test condition: Apply half sine wave voltage with 10kV wave height between A and B in insulation liquid



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AS/EN/JISQ/ 9100:2009 REV C and ISO 9001:2008 Certificate No: 45325

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